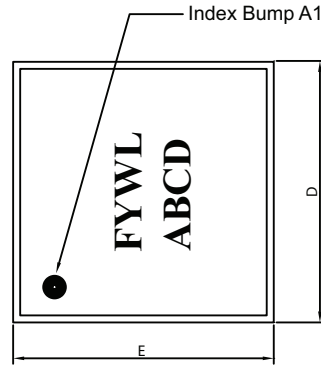
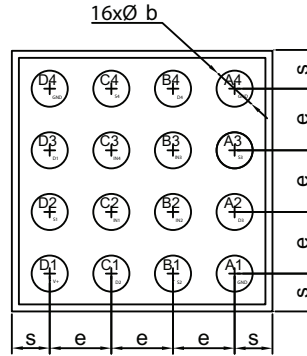


WCSP 4 x 4: 16 Bumps

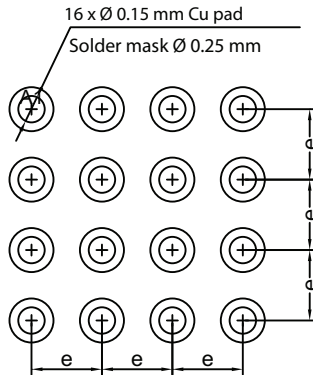
(4 x 4, 0.35 mm pitch, 172 μm bump height, 1.48 mm x 1.48 mm die size)



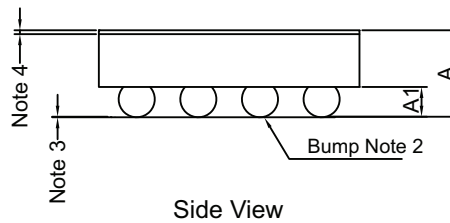
Top View



Bottom View



Recommended Land Pattern (NSMD)



Side View

DWG: 6022

Notes

- (1) Laser mark on the silicon die back, coated with an epoxy film
- (2) Bumps are SAC405
- (3) 0.05 max. co-planarity
- (4) Laminate tape thickness is 0.022 mm

DIM.	MILLIMETERS ^a			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.444	0.474	0.504	0.0175	0.0187	0.0198
A1	0.146	0.172	0.198	0.0057	0.0068	0.0078
b	0.165	0.205	0.245	0.0065	0.0081	0.0096
e	0.350			0.0138		
s	0.175	0.195	0.215	0.0069	0.0077	0.0085
D	1.400	1.440	1.480	0.0551	0.0567	0.0583
E	1.400	1.440	1.480	0.0551	0.0567	0.0583

Note

- a. Use millimeters as the primary measurement.